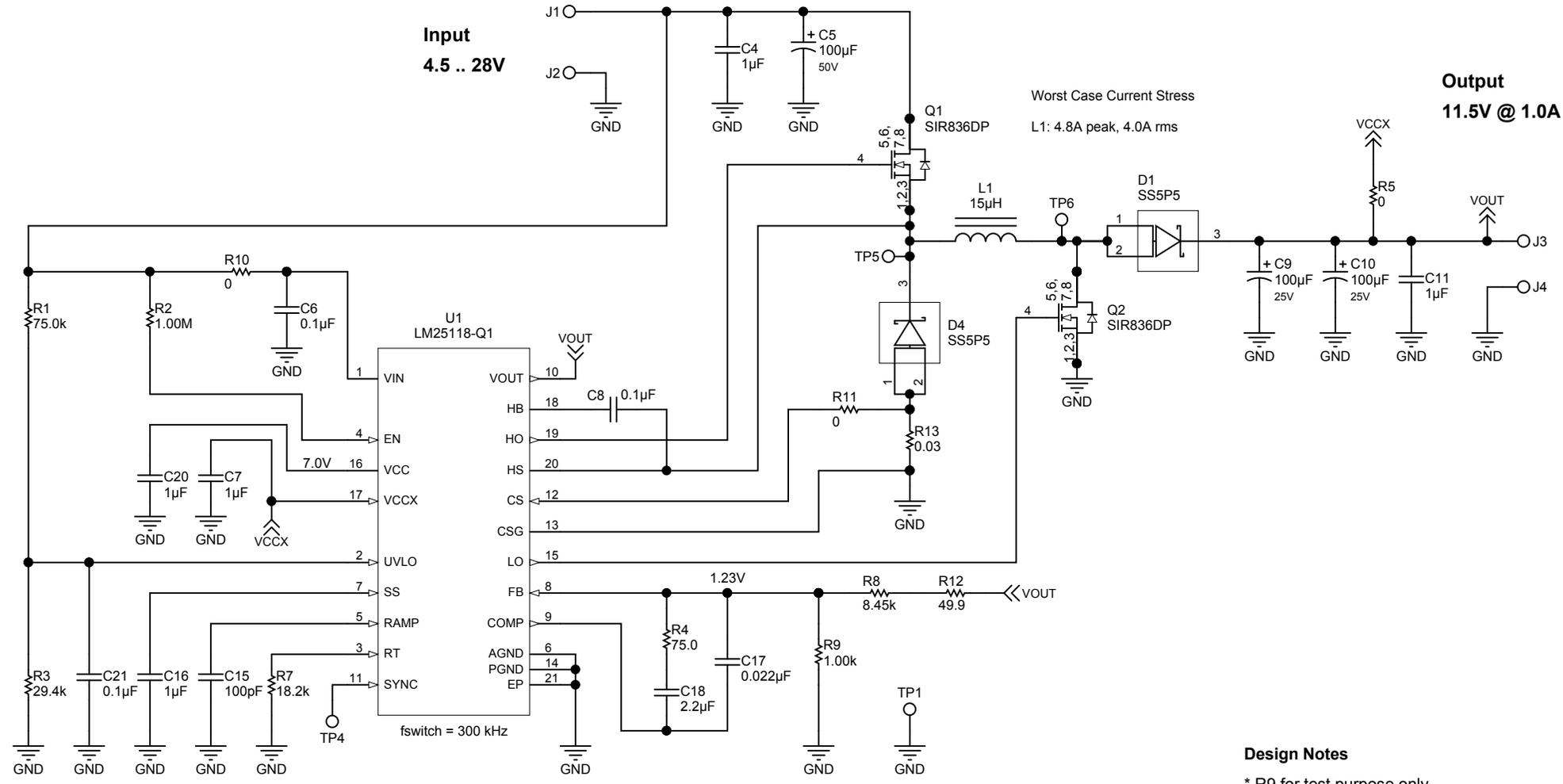


Revision History	
Revision	Notes
A	* Paper Design
B	* Built & Tested



Design Notes
 * R9 for test purpose only
 * RefDes fit AN-1819 LM5118 Evaluation Board

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Number: PMP11773 Rev: B
 SVN Rev: Version control disabled
 Drawn By:
 Engineer: Matthias Ulmann

Designed for: Public Release Mod. Date: 12/9/2015
 Project Title: Automotive Buck-Boost
 Sheet Title:
 Assembly Variant: [No Variations] Sheet: 1 of 1
 File: PMP11773RevB.SchDoc Size: A4
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